What is claimed is:

1. A system comprising:

a defect review tool, wherein the defect review tool has a stage configured to clamp a wafer; and

a controller configured to communicate with the defect review tool, wherein the controller is configured to identify a non-visual defect on a layer of the wafer using a classifier, wherein the controller identifies the non-visual defect by using the classifier to filter at least one of topographical defects, intensity attributes, or energy attributes, wherein the topographical defects include a particle or a scratch, wherein the intensity attributes include a residue or a scum, and wherein the energy attributes include a void.

2. The system of claim **1**, wherein the controller comprises a processor configured to communicate with the defect review tool, a storage device in electronic communication with the processor containing the classifier, and a communication port in electronic communication with the processor for communicating with the defect review tool.

3. The system of claim **1**, wherein the defect review tool is a scanning electron microscope (SEM).

4. The system of claim **1**, wherein the non-visual defect is an SEM non-visual defect (SNV).

5. The system of claim **1**, wherein the classifier is configured to filter the topographical defects.

6. The system of claim **1**, wherein the classifier is configured to filter the intensity attributes.

7. The system of claim **1**, wherein the classifier is configured to filter the energy attributes.

8. A method comprising:

generating, using a defect review tool, an image of a layer on a wafer;

evaluating, using a processor, at least one attribute of the image using a classifier; and

identifying, using the processor, a non-visual defect on the layer of the wafer using the classifier, wherein the processor identifies the non-visual defect by using the classifier to filter at least one of topographical defects, intensity attributes, or energy attributes, wherein the topographical defects include a particle or a scratch, wherein the intensity attributes include a residue or a scum, and wherein the energy attributes include a void.

9. The method of claim **8**, further comprising defining, using the processor, an upper limit and lower limit for non-visual defects, wherein the non-visual defect that is identified is between the upper limit and the lower limit.

10. The method of claim **8**, wherein the classifier filters the topographical defects.

11. The method of claim **8**, wherein the classifier filters the intensity attributes.

12. The method of claim **8**, wherein the classifier filters the energy attributes.

13. The method of claim **8**, wherein the classifier is configured to be used on each layer of the wafer.

14. The method of claim **8**, wherein the generating uses a scanning electron microscope (SEM).

15. The method of claim **8**, wherein the non-visual defect is an SEM non-visual defect (SNV).

16. The method of claim **8**, wherein the comparing and identifying may be performed in real-time with the generating.